

ASB Inc.
831 Tamnip-dong, Yuseong-gu, Daejeon 305-510, Korea

Part Number: Applicable to ASX-series, ASW-series, ASL-series
Product Name: GaAs Amplifier
Package Type: SOT89

Package Elements	Constituents	CAS No.	Weight (mg)	Weight %
Active Semiconductor Die	GaAs	1303-00-0	0.5890	100
Leadframe	Cu	7440-50-8	18.8016	99.28
	Zn	7440-66-6	0.0417	0.22
	Sn	7440-31-5	0.0473	0.25
	Cr	7440-47-3	0.0473	0.25
Leadframe Plating	Sn	7440-31-5	0.3870	99.9
Epoxy Molding Compound	Silica Fused	60676-86-0	5.1530	86.20
	Epoxy Resin	129915-35-1	0.3587	6.00
	Epoxy, Cresol Novolac	29690-82-2	0.0897	1.50
	Phenol Resin	26834-02-6	0.3587	6.00
	Carbon Black	1333-86-4	0.0179	0.30
Epoxy Resin	Silver	7440-22-4	0.0270	75.00
	Epoxy Resin	129915-35-1	0.0054	15.00
	Aliphatic anhydride	-	0.0029	8.00
	2-butoxyethyl acetate	112-07-2	0.0004	1.00
	Polymeric material	-	0.0004	1.00
Wire	Au	7440-57-5	2.8040	100
Total			28.736	

This information sheet is to declare all substances intentionally added in our SOT89 semiconductor products. Total weight of the package varies depending on active die size. The material data is evidenced by written declaration from our packaging company. The products listed above DO NOT CONTAIN intentionally added hazardous materials such as lead (Pb), cadmium (Cd), mercury (Hg), hexavalent chromium (Cr⁶⁺), polybrominated biphenyls (PBBs), and polybrominated diphenylethers (PBDEs) and **COMPLY with the EU RoHS Directive 2002/95/EC**. For further information, contact our Sales Department at sales@asb.co.kr.


Authorized Signature, ASB Inc.

This data is based on information provided by our suppliers and we do not validate it by measurement. ASB Inc. assumes no responsibility in connection with any use of this information. The information is subject to change without notice.
© Copyrights ASB Inc., 2009.